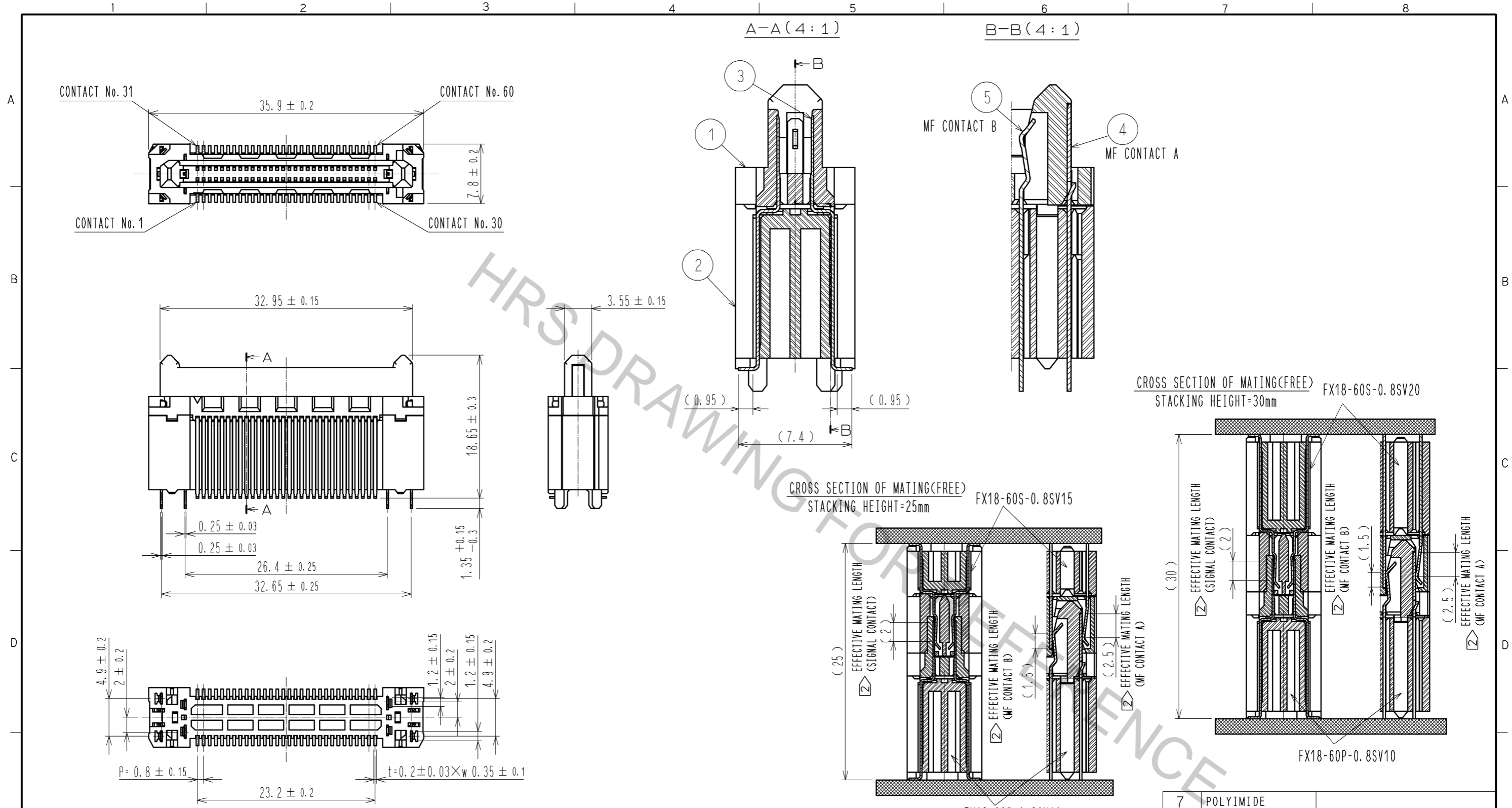


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- NOTE 1 LEAD CO-PLANARITY IS 0.1mm MAX.
- ② CONTACTS ARE 3 STEPS SEQUENTIAL. (MF CONTACT A->SIGNAL CONTACT->MF CONTACT B) WHEN USING THIS SEQUENTIAL STRUCTURE, PLEASE AVOID ANGLED INSERTION.
- ③ MF CONTACT A AND MF CONTACT B CAN BE USED AS POWER SUPPLY CONTACT. (3A/PIN MAX)
- ④ IT SHOWS THE VACUUM PICKUP AREA. (SEE PAGE 2)  
REMOVE THE MYLAR TAPE BEFORE MATING CONNECTORS.
- ⑤ THIS IS PACKAGED IN TRAY. (60pcs/TRAY)
- ⑥ BLEMISH AND HIT MARK CAN BE OCCURED THROUGH OUT THE MANUFACTURING PROCESS WHICH DOESN' T AFFECT QUALITY LEVEL.
- ⑦ THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCES.

NO.	MATERIAL	FINISH	REMARKS	NO.	MATERIAL	FINISH	REMARKS
3	PHOSPHOR BRONZE		CONTACT AREA:GOLD 0.1 μm LEAD AREA:GOLD 0.03 μm UNDER PLATING:NICKEL 1.3 μm	5	COPPER ALLOY		CONTACT AREA:GOLD 0.1 μm LEAD AREA:TIN-PLATING 1 μm UNDER PLATING:NICKEL 1.3 μm
2	POLYAMIDE	BLACK	UL94V-0	4	COPPER ALLOY		CONTACT AREA:GOLD 0.1 μm LEAD AREA:TIN-PLATING 1 μm UNDER PLATING:NICKEL 1.3 μm
1	POLYAMIDE	BLACK	UL94V-0				

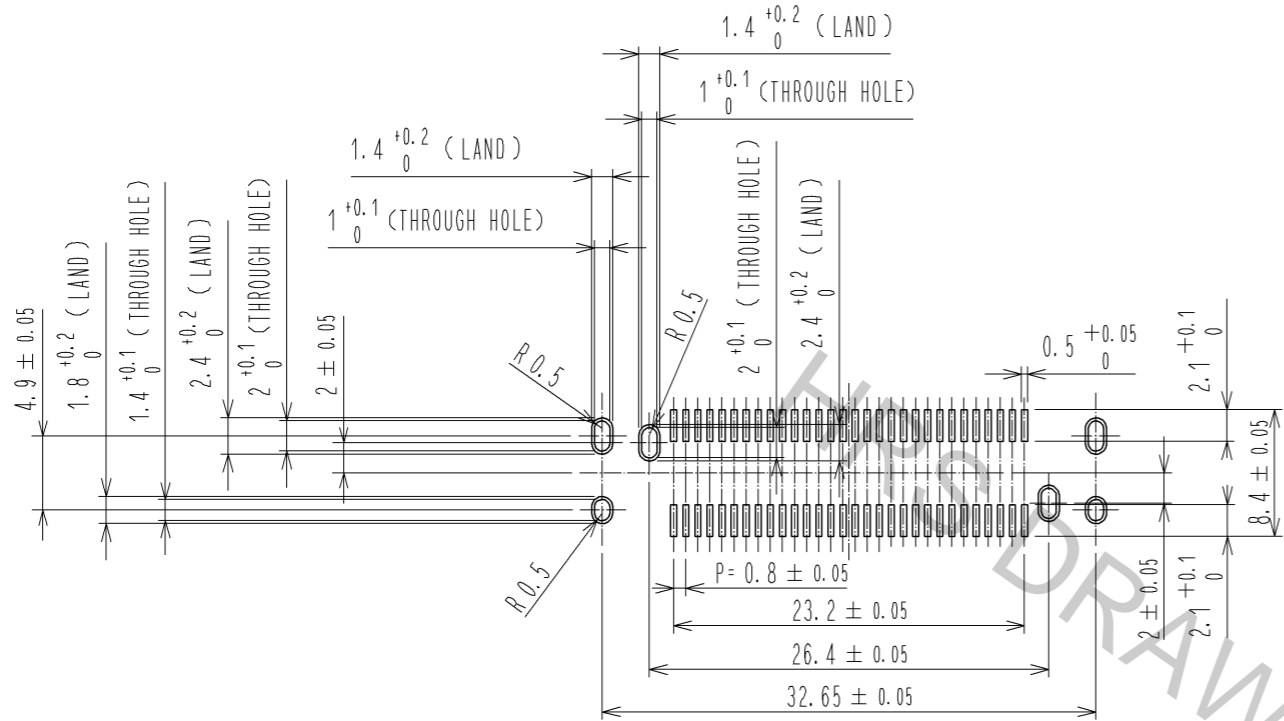
UNITS	SCALE	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm	2 : 1	△				

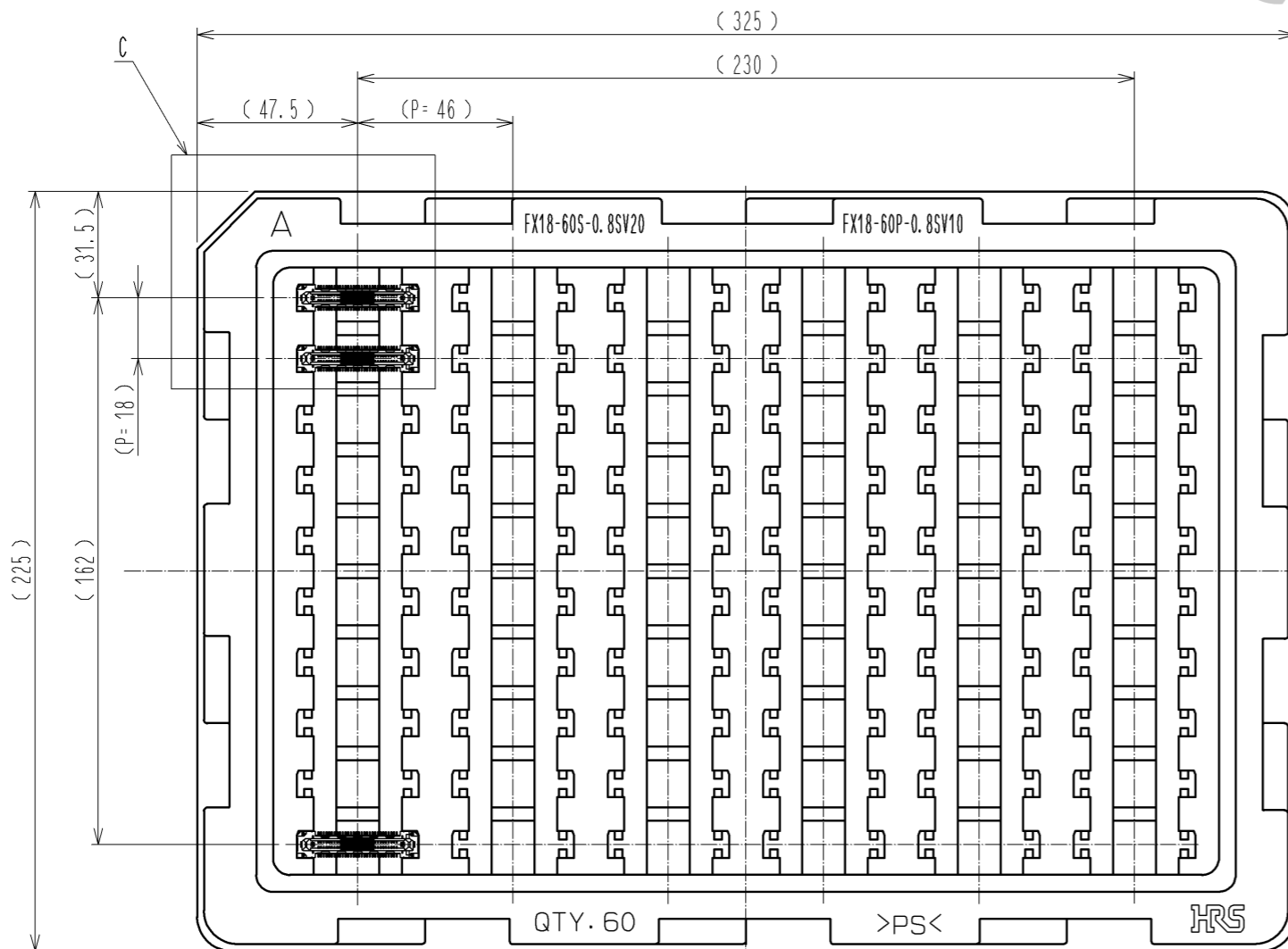
APPROVED	CHECKED	DESIGNED	DRAWN	DATE	DRAWING NO.	PART NO.	CODE NO.
HS. OKAWA	KI. HIROKAWA	TH. SANO	TH. SANO	11.08.24	EDC3-334383-00	FX18-60P-0.8SV10	CL579-0023-5-00

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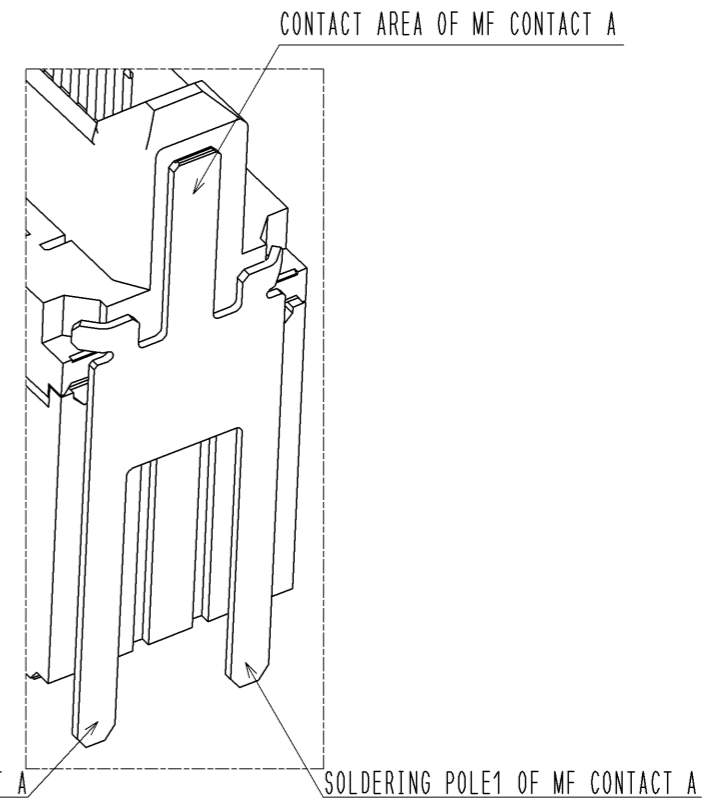
RECOMMENDED LAND PATTERN DIMENSION OF PCB(2:1)  
(PCB THICKNESS:t=1.6mm METAL MASK THICKNESS:t=0.12mm)



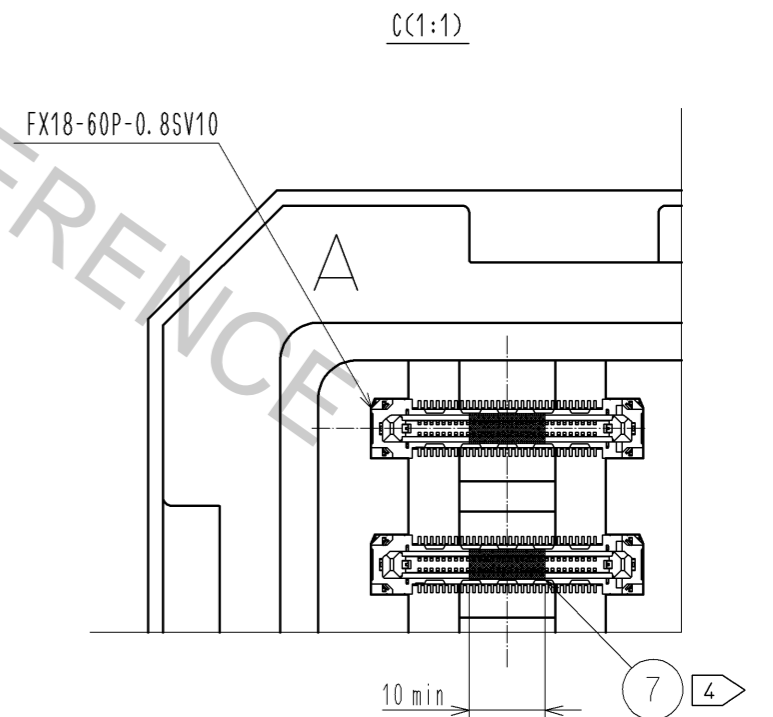
5 DRAWING FOR PACKING(1:2)



8 CONFIGURATION OF MF CONTACT A



NOTE 8 SOLDERING LEAD OF MF CONTACT A SPLITS INTO TWO POLES.  
BE SURE TO CONNECT TO THE SAME CIRCUIT.



<b>HRS</b>	DRAWING NO.	EDC3-334383-00
	PART NO.	FX18-60P-0.8SV10
	CODE NO.	CL579-0023-5-00
		△ 2/2